

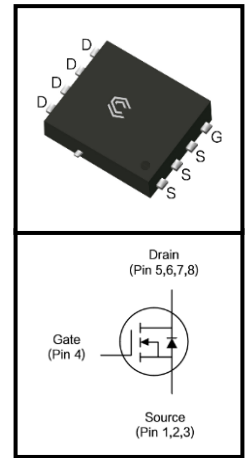
40V N-Channel MOSFET

FEATURES

- Super Low Gate Charge
- 100% EAS Guaranteed
- RoHS compliant
- Green Device Available
- Excellent C^*dV/dt effect decline
- Advanced high cell density Trench technology

APPLICATIONS

- Load Switching
- Hard switched and high frequency circuits
- Uninterruptible power supply



Device Marking and Package Information

Device	Package	Marking
CSN04N2P1	PDFN5 × 6	CSN04N2P1

Absolute Maximum Ratings $T_C = 25^\circ\text{C}$, unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-Source Voltage ($V_{GS} = 0V$)	V_{DSS}	40	V
Continuous Drain Current	I_D	160	A
Pulsed Drain Current (note1)	I_{DM}	640	A
Gate-Source Voltage	V_{GSS}	± 20	V
Single Pulse Avalanche Energy (note2)	E_{AS}	198.8	mJ
Avalanche Current (note1)	I_{AS}	23.4	A
Repetitive Avalanche Energy (note1)	E_{AR}	0.8	mJ
Power Dissipation ($T_C = 25^\circ\text{C}$)	P_D	108.3	W
Operating Junction and Storage Temperature Range	T_J, T_{stg}	$-55 \sim +150$	$^\circ\text{C}$

Thermal Resistance

Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (note3)	R_{thJC}	1.15	$^\circ\text{C/W}$
Thermal Resistance, Junction-to-Ambient	R_{thJA}	62.5	

Specifications $T_J = 25^{\circ}\text{C}$, unless otherwise noted

Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
Static						
Drain–Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	40	--	--	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 40V, V _{GS} = 0V, T _J = 25°C	--	--	1	uA
Gate–Source Leakage	I _{GSS}	V _{GS} = ± 20V	--	--	± 100	nA
Gate–Source Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	1.0	--	2.5	V
Drain–Source On–Resistance (note4)	R _{DS(on)}	V _{GS} = 10V, I _D =20A	--	1.6	2.1	mΩ
		V _{GS} = 4.5V, I _D =15A	--	2.2	2.8	mΩ
Dynamic						
Input Capacitance	C _{iss}	V _{GS} = 0V, V _{DS} = 20V, f = 1.0MHz	--	3403	--	pF
Output Capacitance	C _{oss}		--	1683	--	
Reverse Transfer Capacitance	C _{rss}		--	114	--	
Gate Resistance	R _g	V _{GS} = 0V,f = 1 MHz	--	2.00	--	Ω
Total Gate Charge	Q _g	V _{DD} = 32V, I _D = 50A, V _{GS} = 10V	--	60.9	--	nC
Gate–Source Charge	Q _{gs}		--	5.4	--	
Gate–Drain Charge	Q _{gd}		--	9.0	--	
Turn–on Delay Time	t _{d(on)}	V _{DD} =20V, I _D = 50A, R _G = 3.1Ω	--	13	--	ns
Turn–on Rise Time	t _r		--	35	--	
Turn–off Delay Time	t _{d(off)}		--	48	--	
Turn–off Fall Time	t _f		--	20	--	
Drain–Source Body Diode Characteristics						
Continuous Body Diode Current	I _S	T _C = 25 °C	--	--	160	A
Pulsed Diode Forward Current	I _{SM}		--	--	640	
Body Diode Voltage	V _{SD}	T _J = 25°C, I _{SD} = 20A, V _{GS} = 0V	--	--	1.2	V
Reverse Recovery Time	t _{rr}	V _{DD} = 20V,I _S = 50A, di _F /dt =100A / μ s	--	61	--	ns
Reverse Recovery Charge	Q _{rr}		--	0.027	--	uC

Notes

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. $L=0.5mH, V_{DD} = 20V, R_G = 25 \Omega$, Starting $T_J = 25^{\circ}\text{C}$
3. Reference standard for thermal resistance testing: JESD51-14
4. Pulse Test: Pulse width $\leq 300 \mu s$, Duty Cycle $\leq 1\%$

Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Figure 1. Output Characteristics ($T_J = 25^\circ\text{C}$)

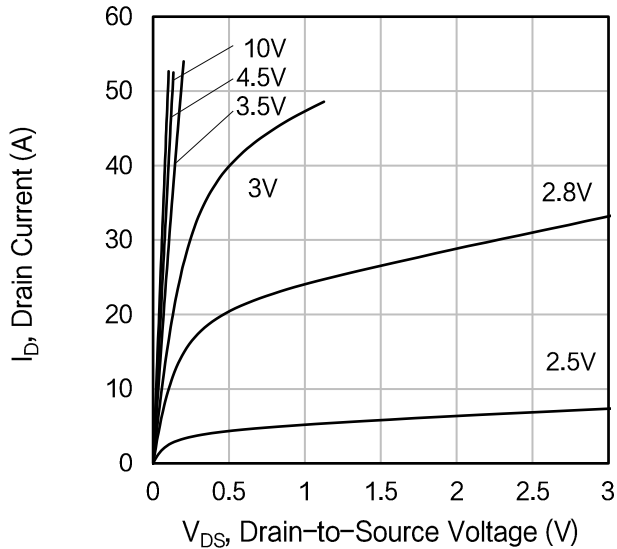


Figure 2. Body Diode Forward Voltage

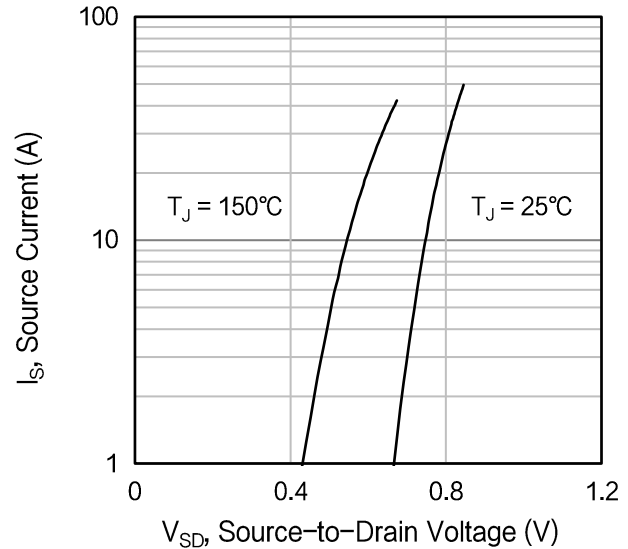


Figure 3. Drain Current vs. Temperature

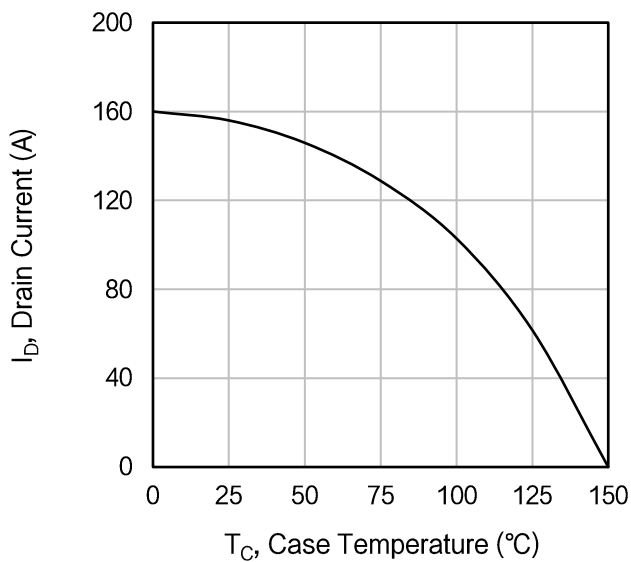


Figure 4. BV_{DSS} Variation vs. Temperature

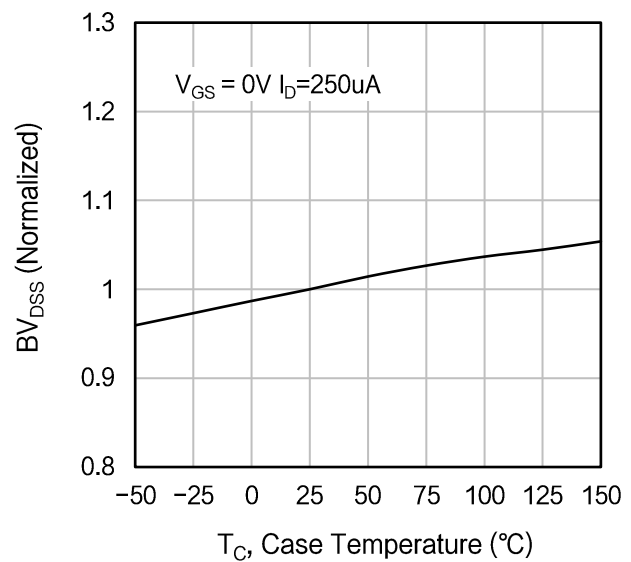


Figure 5. Transfer Characteristics

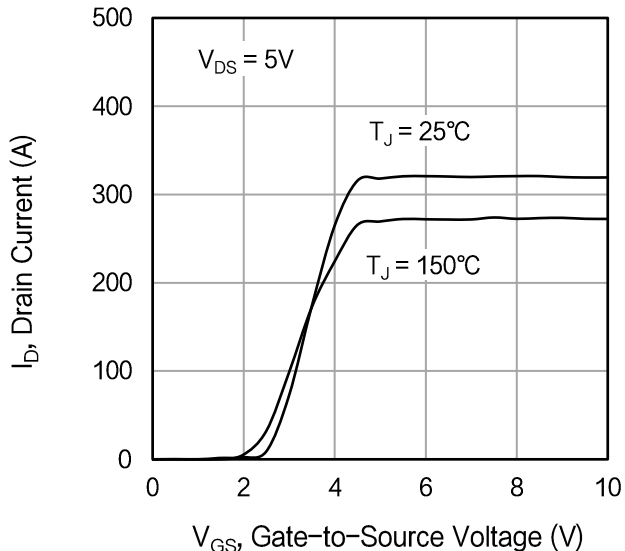
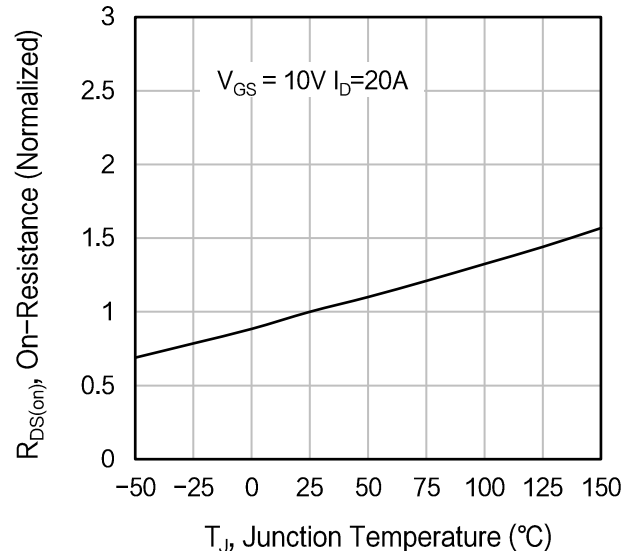


Figure 6. On-Resistance vs. Temperature



Typical Characteristics $T_J = 25^\circ\text{C}$, unless otherwise noted

Fig.7 Threshold Voltage vs. Temperature

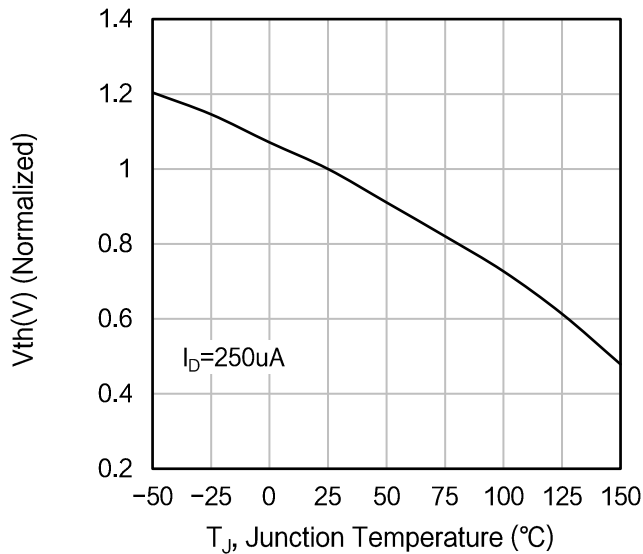


Figure 8. On-Resistance vs. Drain Current

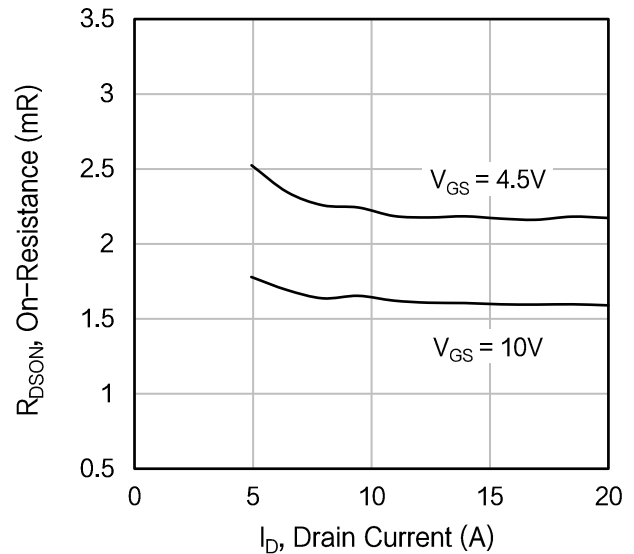


Figure 9. Capacitance

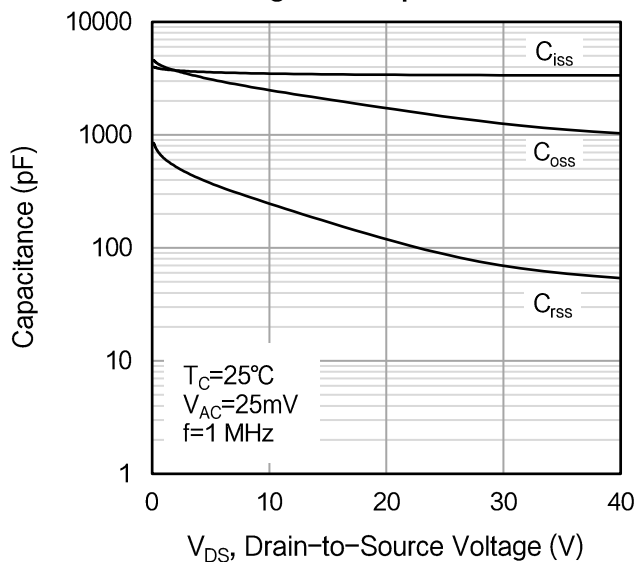


Figure 10. Gate Charge

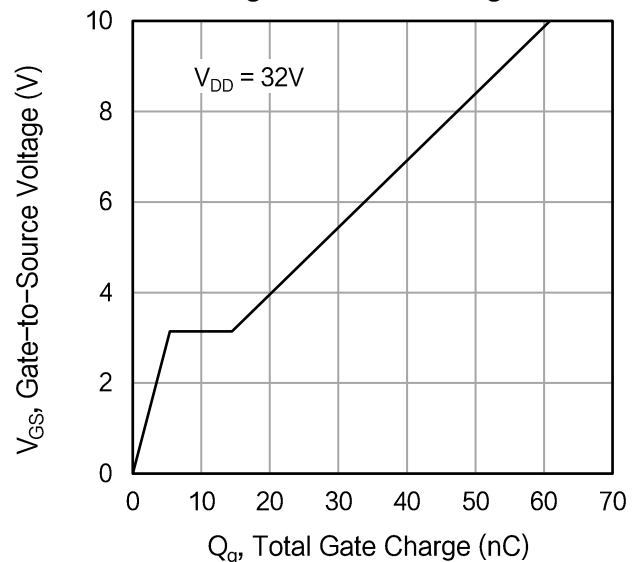


Figure 11. Safe Operating Area

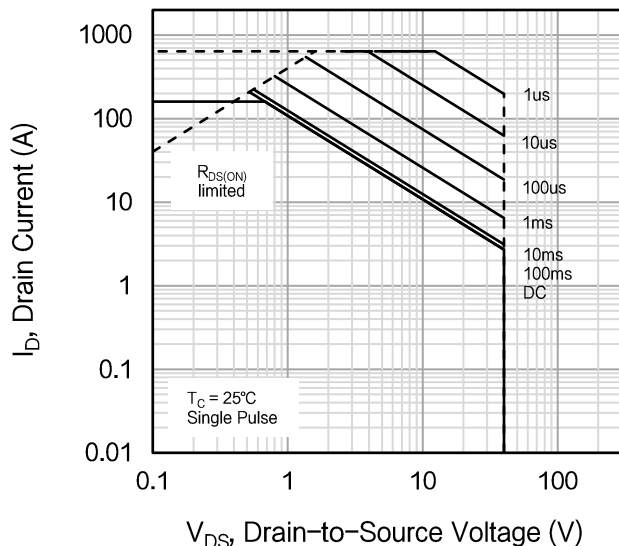
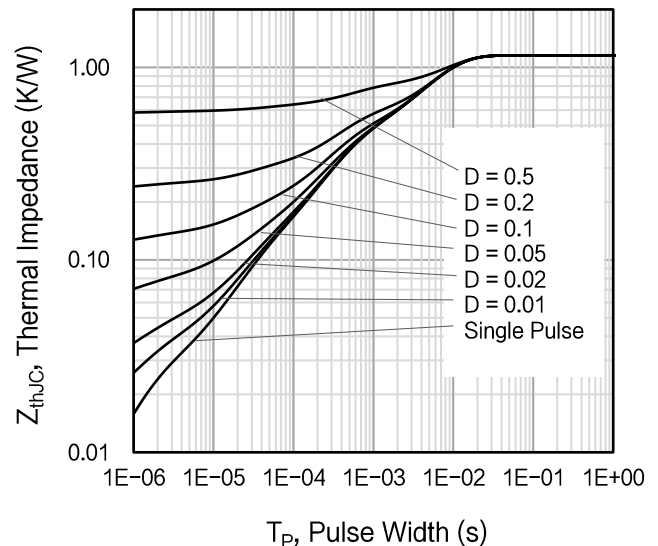


Figure 12. Transient Thermal Impedance



Typical Characteristics $T_J = 25^{\circ}\text{C}$, unless otherwise noted

Fig.13 D-S Leakage Current vs. D-S Voltage

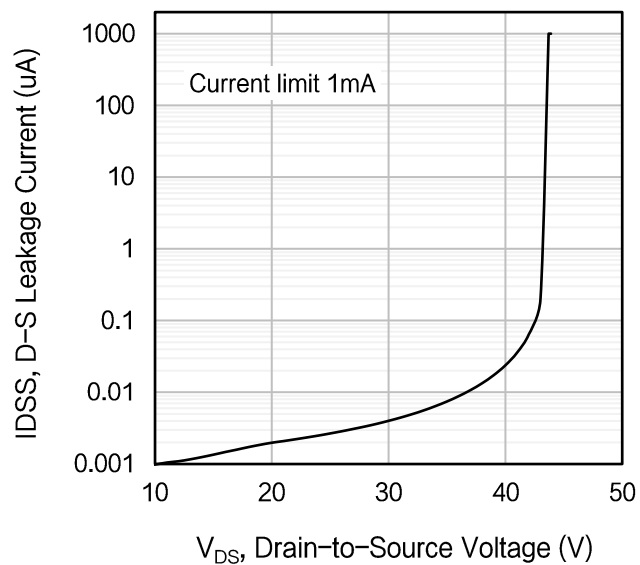


Figure 14. G-S Leakage Current vs. G-S Voltage

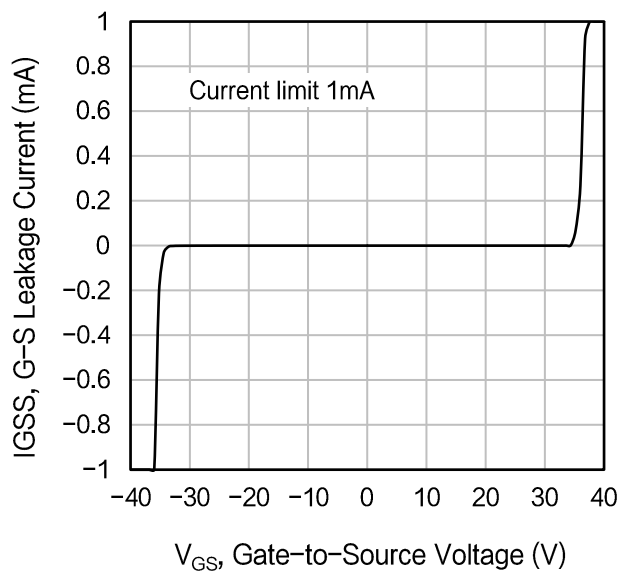


Figure A: Gate Charge Test Circuit and Waveform

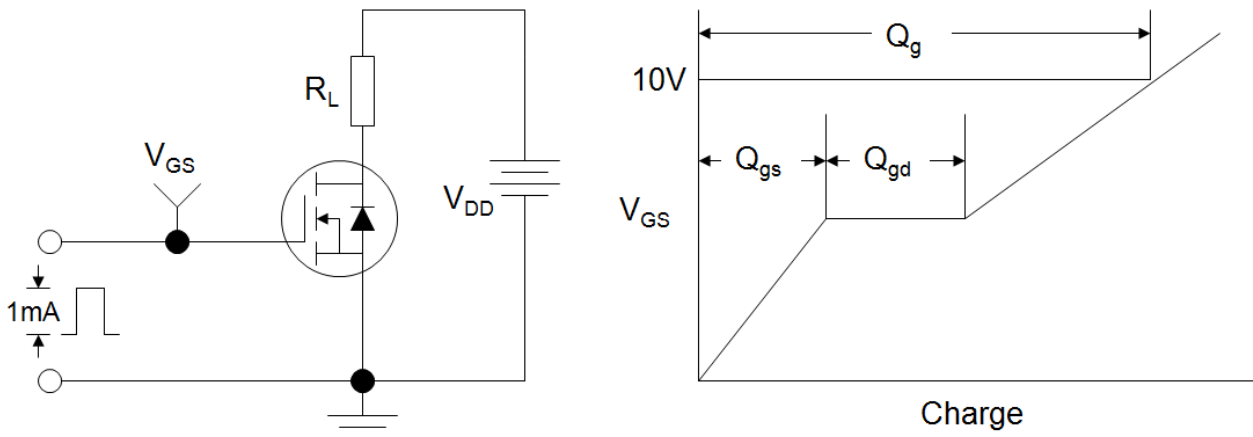


Figure B: Resistive Switching Test Circuit and Waveform

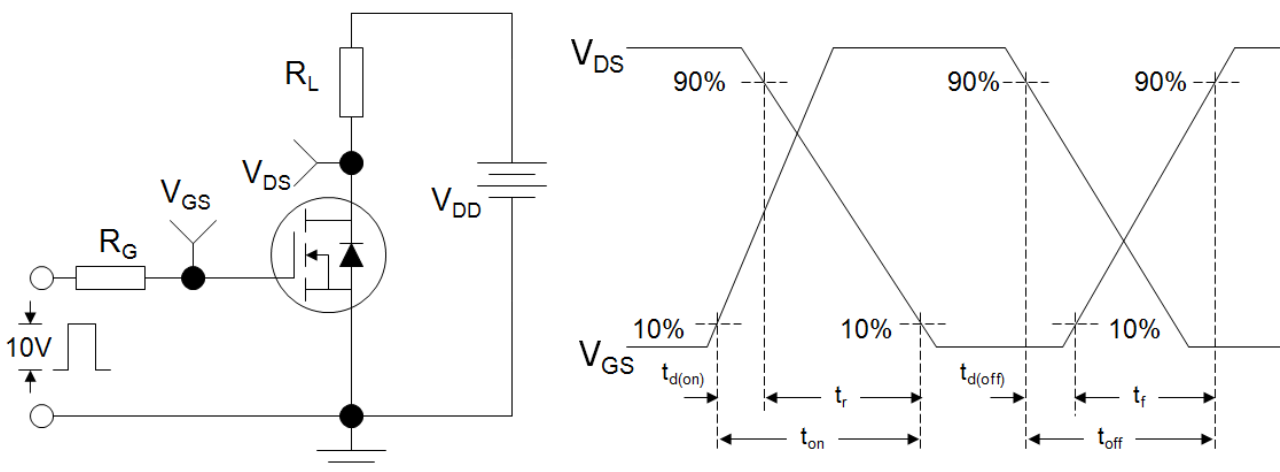
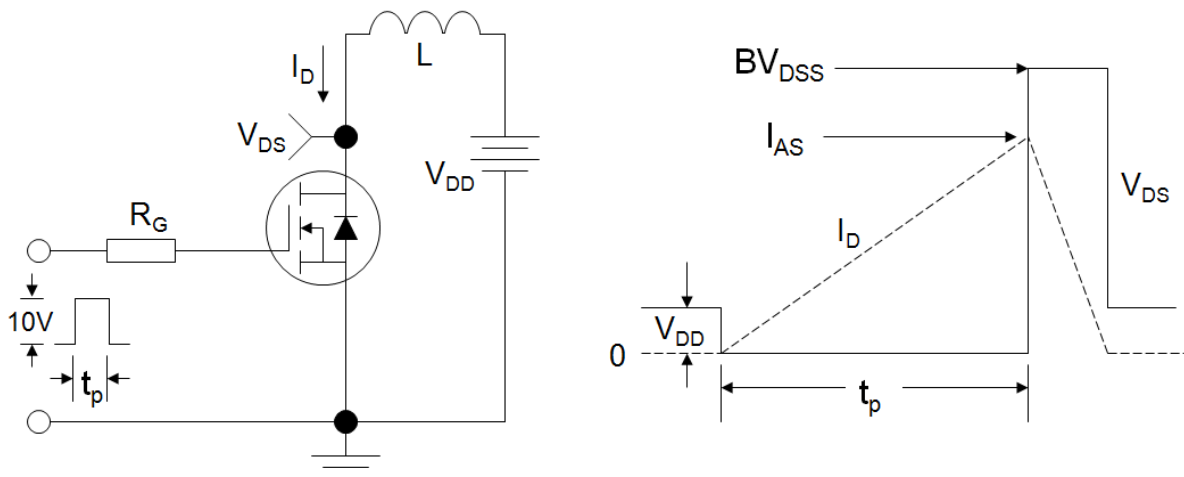
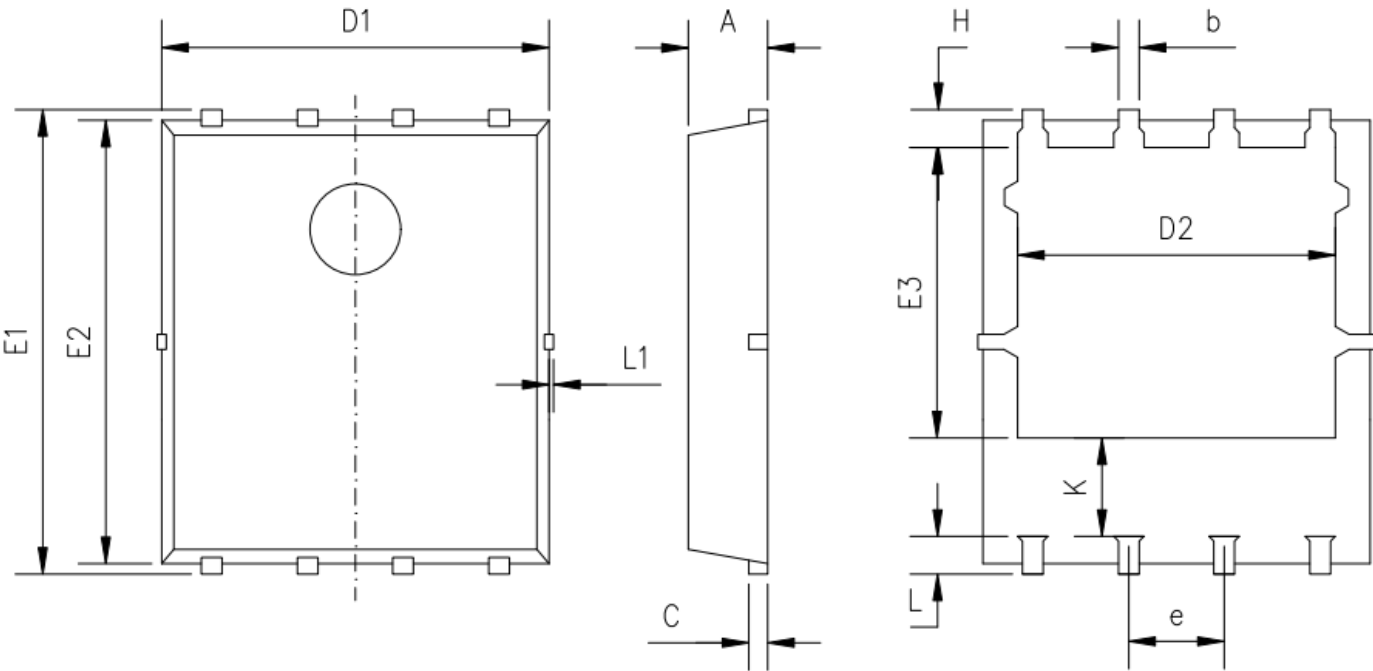


Figure C: Unclamped Inductive Switching Test Circuit and Waveform



PDFN5 × 6



SYMBOLS	MILLIMETERS	
	MIN	MAX
A	0.90	1.20
b	0.25	0.50
C	0.10	0.35
D1	4.80	5.40
D2	3.72	4.25
e	1.17	1.37
E1	5.90	6.35
E2	5.60	6.06
E3	3.33	3.92
H	0.40	0.71
L	0.30	0.84
L1	0.00	0.15
K	1.00	1.50

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